



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20230306005.0
Marking Standardization for Select Devices
Information Only**

Date: March 16, 2023
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20230306005.0
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months (60 months for Automotive devices). The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS1220IPW	null
AM26LV32EIPWR	null
CD40109BPW	null
CD4094BPWR	null
CD4520BPW	null
INA240A1PWR	null
INA240A2PWR	null
INA240A3PWR	null
INA240A4PWR	null
MAX3232ECPWR	null
SN74LVC157APWRG4	null
TPS2112APWR	null
TRS3221EIPWR	null
CD74HC4053PWR	null

Technical details of this Product Change follow on the next page(s).



PCN Number:	20230306005.0	PCN Date:	March 16, 2023
Title:	Marking Standardization for Select Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Datasheet
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Device Marking
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change

PCN Details



Description of Change:

This notice is to communicate an update in the device symbolization format for the devices in the product affected selection above as follows:

Change #1: All devices in this notice will start having the mold cavity id included in the device marking for enhanced device level traceability as follows:

	Current	New
Visual		
Pin 1 mark	Embossed	Dot

Change #2: Devices Symbolization update (for this change below, some of the devices were already on PCN20211123002 for this change):

	Current	New
**ECAT	Include Value	Remove
TI Bug	Include	Replace with "TI" text
Example	 <p>13.10s (109.9 PPH)</p>	 <p>18.52s (116.6 PPH)</p>

** - Not all devices have ECAT information included in the symbolization, but for the ones that do, this information will be removed.

Reason for Change:

Marking Standardization

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Device symbolization

Product Affected:

See page 2 above

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com

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